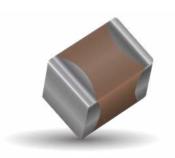
RF/Microwave Capacitors

RF/Microwave Multilayer Capacitors (MLC)

900C Series X7R Ceramic RF Power Multilayer Capacitors





GENERAL DESCRIPTION

KYOCERA AVX, the industry leader, offers new improved ESR/ESL performance for the 900 C Series RF Capacitors. This Series exhibits superior volumetric efficiency, providing high levels of capacitance for HF/ RF power applications. Ceramic construction provides a rugged, hermetic package.

KYOCERA AVX offers an encapsulation option for applications requiring extended protection against arc-over and corona.

FEATURES

- Case C Size (.250" x .250")
- · Low ESR / ESL
- Rugged Construction
- · Encapsulation Option Available *
- · Capacitance Range $0.01\mu F$ to $1 \mu F$
- Mid-K
- High Reliability

PACKAGING OPTIONS









Tape & Reel

Orientation Tape & Reel

Special **Packaging Available**

Cap-Pak® (100 pcs)



FUNCTIONAL APPLICATIONS

- Bypass
- DC Blocking
- Coupling

TYPICAL CIRCUIT APPLICATIONS

- · HF/RF Power Amplifiers
- · Medical Electronics.
- High Frequency Switch Mode **Power Supplies**
- *For leaded styles only.

ENVIRONMENTAL CHARACTERISTICS

Thermal Shock	MIL-STD-202, Method 107, Condition A.
Moisture Resistance	MIL-STD-202, Method 106.
Low Voltage Humidity	MIL-STD-202, Method 103, Condition A, with 1.5 Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours min.
Life Test	MIL-STD-202, Method 108, for 2000 hours, at 125°C. 200% WVDC applied.
Solderability	Mil-STD-202, Method 208
Terminal Strength	Terminations for chips and pellets withstand a pull of 5 lbs. min., 10 lbs. typical, for 5 seconds in direction perpendicular to the termination surface of the capacitor.

ELECTRICAL SPECIFICATIONS

Dissipation Factor (DF)	2.5% max. at 1 KHz
Temperature Coefficient of Capacitance (Tcc)	Less than ±15% (-55°C to +125°C)
Insulation Resistance (IR)	0.01 MFd to 1 MFd 1000 megohms min. @ +25°C at rated WVDC. 100 megohms min. @ +125°C at rated WVDC.
Working Voltage (WVDC)	See Capacitance Values Table
Dielectric Withstanding Voltage (DWV)	Case C: 250% of rated WVDC for 5 secs.
Aging Effects	3% maximum per decade hour
Piezoelectric Effects	Negligible
Dielectric Absorption	2% typical
Operating Temperature Range	-55°C to +125°C (No derating of working voltage)
Termination Styles	Available in various surface mount and leaded styles. See Mechanical Configurations
Terminal Strength	Terminations for chips and pellets withstand a pull of 10 lbs. min., 15 lbs. typical, for 5 seconds in direction perpendicular to the termina-tion surface of the capacitor. Test per MIL-STD-202, method 211.

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CAPACITANCE VALUES

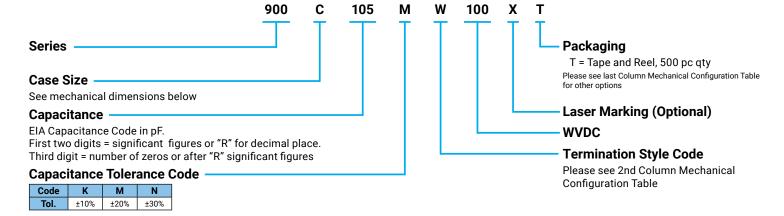
Cap. Code	Cap. (Mfd)	Tol.	Rated Wvdc
103	.010		300
153	.015		300
223	.022		300
333	.033		250
473	.047		250
683	.068		250
104	.10	IZ M NI	200
154	.15	K, M, N	200
224	.22		200
334	.33		150
474	.47		150
684	.68		150
824	.82		100
105	1.0		100

Code	K	М	N
Tol.	±10%	±20%	±30%

VRMS = 0.707 X WVDC

- SPECIAL VALUES, TOLERANCES, HIGHER WVDC AND MATCHING AVAILABLE.
- ENCAPSULATION OPTION AVAILABLE. PLEASE CONSULT FACTORY.

HOW TO ORDER



The above part number refers to a 900 C Series (case size C) 1.0 MFd capacitor, M tolerance (±20%), 100 WVDC, with W termination (Tin/Lead, Solder Plated over Nickel Barrier), laser marking and ATC Matrix Tray packaging.

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MECHANICAL CONFIGURATIONS

Series		Case Size	Outlines	В			Lead And Termination Dimensions And Materials		Pkg				
& Case Size	Term. Code	& Type	W/T Is A Termination Surface	Length (L)	Width (W)	Thickness (T)	Overlap (Y)	Materials Materials	Pkg Type & Qty	Code			
900C	w	C Solder Plate	Y→ ← ↓ w	.230+.020 010 (5.84 +0.51 -0.25)		(1)					Tin/Lead, Solder Plated over Nickel Barrier Termination	T250 T & R 500 Cap PaK 36	T250 T C36
900C	Р	C Pellet	Y→ ← ↓ w	.230+.025 010 (5.84 +0.64 -0.25)				Heavy Tin/Lead Coated, over Nickel Barrier Termination	T250 T&R 500 Cap PaK 36	T250 T C36			
900C	Т	Solderable Nickel Barrier	Y→ ←	.230 +.020 010 (5.84 +0.51 -0.25					RoHS Compliant Tin Plated over Nickel Barrier Termination	T250 T & R 250 Cap PaK 36	T250 T C36		
900C	MS	C Microstrip	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$.250 ±.015	.145 (3.68) max. for capacitance values < 0.82 MFd;		High Purity Silver Leads LL = .500 (12.7) min. WL = .240 ±.005 (6.10 ±.127) TL = .004 ±.001 (.102 ±.025) Leads are Attached with High Temperature Solder.	Cap Pak 24	C24			
900C	AR	C Axial Ribbon	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$.250 ±.015 (6.35 ±0.38)	.165 (4.19) max. for capacitance values			Box, 24	B24			
900C	AW	C Axial Wire	→ LL	.245 ±.025 (6.22 ±0.64)	(6.22 ±0.64)		values ≥0.82 MFd.	N/A	Silver-plated Copper Leads LL = 1.0 (25.4) min. Dia. = .032 ±.002 (0.81 ±0.05	Cap Pak 24	C24		
900C	VA	C Veritical Axial Ribbon						Silver Leads LL = .500 (12.7) min. WL = * See below TL = .004 ±.001 (.102 ±.025)	Cap Pak 24	C24			
900C	RW	C Radial Wire	→ L ← → W ←					Silver-plated Copper Leads LL = 1.0 (25.4) min. Dia. = .032 ±.002 (0.81 ±0.05)	Cap Pak 24	C24			

Custom lead styles and lengths are available; consult factory. All leads are high purity silver attached with high temperature solder and are RoHS compliant. ** WL = .110 (2.79) for capacitance values < 0.82 MFd.; WL = .130 (3.30) for capacitance values \geq 0.82 MFd.

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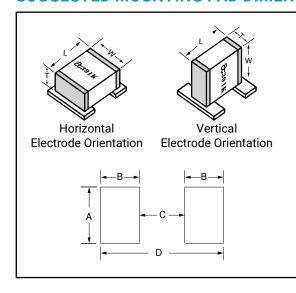


NON-MAGNETIC MECHANICAL CONFIGURATIONS

Series & Case	Term. Code	Case Size	Outlines W/T Is A	Body Dimensions Inches (Mm)				Pkg Type & Qty	Pkg Code		
Size	Code	& Type	Termination Surface	Length (L)	Length (L) Width (W) Thickness (T)		Overlap (Y)	Materials	& QIY	Code	
900C	WN	C Non-Mag Solder Plate	$\begin{array}{c c} Y \rightarrow \parallel \longleftarrow & \downarrow \\ \hline & W \\ \hline \rightarrow & L & \longleftarrow \uparrow \rightarrow \mid T \mid \longleftarrow \end{array}$.230 +.025010 (5.84 + 0.64-0.25)	250 + 015 < 0.82 N		.145 (3.68) max. < 0.82 MFd	.040 (1.02)	Tin/Lead, Solder Plated over Non-Magnetic Barrier Termination	T & R 500 Cap PaK 36	T C36
900C	TN	C Non-Mag Solderable Barrier	Y→ ←	.230 +.025010 (5.84 + 0.64-0.25)	(6.35 ±0.38)	.165 (4.19) max. ≥0.82 MFd	màx. ´	RoHS Compliant Tin Plated over Non-Magnetic Barrier Termination	T & R 500 Cap PaK 36	T C36	

Custom lead styles and lengths are available; consult factory. All leads are high purity silver attached with high temperature solder and are RoHS

SUGGESTED MOUNTING PAD DIMENSIONS



Case C Vertical Mount								
Cap Value Pad Size A Min. B Min. C Min. D Min.								
< .82 µF	Normal	.150	.050	.200	.300			
	High Density	.130	.030	.200	.260			
> 02 HE	Normal	.185	.050	.200	.300			
	High Density	.165	.030	.200	.260			

Horizontal Mount								
All Walana	Normal	.150	.050	.200	.300			
All Values	High Density	.130	.030	.200	.260			

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PERFORMANCE DATA

